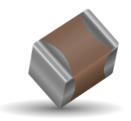
Y5V Dielectric, KGM Series

General Specifications



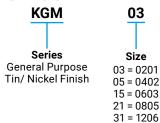


GENERAL DESCRIPTION

Y5V formulations are for general-purpose use in a limited temperature range. They have a wide temperature characteristic of +22% −82% capacitance change over the operating temperature range of −30°C to +85°C.

These characteristics make Y5V ideal for decoupling applications within limited temperature range.

HOW TO ORDER





32 = 1210





Voltage

0G = 4.0V0J = 6.3V1A = 10V 1C = 16V 1E = 25V1H = 50V

0J



+Number of zeros eg. $10\mu F = 106$ 10nF = 103 47pF = 470

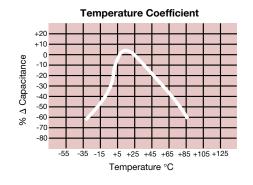


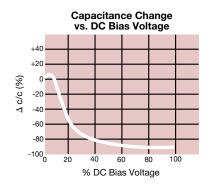


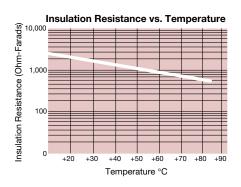


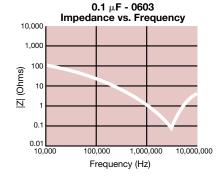
PACKAGING CODES

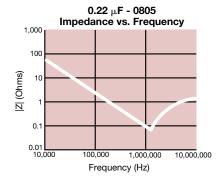
Code	EIA (inch)	IEC(mm)	7" Paper	7" Embossed	13" Paper	13"Embossed
03	0201	0603	Н		N	
05	0402	1005	Н		N	
15	0603	1608	Т		М	
21	0805	2012		U		L
31	1206	3216		U		L
32	1210	3225		U		L

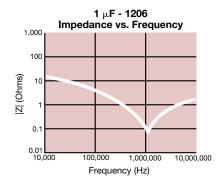












Y5V Dielectric, KGM Series





Parame	ter/Test	Y5V Specification Limits	Measuring (Conditions					
Operating Tem	perature Range	-30°C to +85°C	Temperature Cycle Chamber						
Capac	itance	Within specified tolerance	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 μF, 0.5Vrms @ 120Hz						
Dissipati	on Factor	≤ 5.0% for ≥ 50V DC rating ≤ 7.0% for 25V DC rating ≤ 9.0% for 16V DC rating ≤ 12.5% for ≤ 10V DC rating							
Insulation	Resistance	10,000MΩ or 500MΩ - μ F, whichever is less	Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity						
Dielectric	Strength	No breakdown or visual defects	Charge device with 250% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)						
	Appearance	No defects	Deflectio	n: 2mm					
Resistance to	Capacitance Variation	≤ ±30%	Test Time: 3	0 seconds 1 mm/sec					
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)	l v						
	Insulation Resistance	≥ Initial Value x 0.1	90 r	nm ———					
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.5						
	Appearance	No defects, <25% leaching of either end terminal							
	Capacitance Variation	≤ ±20%							
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.						
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	g electrical properties.					
	Dielectric Strength	Meets Initial Values (As Above)		,					
	Appearance	No visual defects	Step 1: -30°C ± 2°	30 ± 3 minutes					
	Capacitance Variation	≤ ±20%	Step 2: Room Temp	≤ 3 minutes					
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes					
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes					
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 ±2 hours at room temperature						
	Appearance	No visual defects	-						
	Capacitance Variation	≤ ±30%	Charge device with twice rated voltage in test						
Load Life	Dissipation Factor	≤ Initial Value x 1.5 (See Above)	for 1000 hou						
	Insulation Resistance	≥ Initial Value x 0.1 (See Above)	Remove from test chamb temperature for 24 ± 2 h						
	Dielectric Strength	Meets Initial Values (As Above)							
	Appearance	No visual defects	_						
	Capacitance Variation	≤ ±30%	Store in a test chamber set at 85°C ± 2°C/ 85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied.						
Load Humidity	Dissipation Factor	≤ Initial Value x 1.5 (See above)							
. id.indity	Insulation Resistance	≥ Initial Value x 0.1 (See Above)	Remove from chamber temperature an 24 ± 2 hours bef	d humidity for					
	Dielectric Strength	Meets Initial Values (As Above)	27 ± 2 Hours ber	ore measuring.					

Y5V Dielectric, KGM Series





SIZE		02	01		0402			06	03			08	05		1206				1210			
Soldering		Reflov	v Only	Reflow/ Wave		Reflow/ Wave			F	Reflow	/ Wav	e	Reflow/ Wave				Reflow/ Wave			e		
Packaging		All P	All Paper		All Paper			All Paper			Paper/ Embossed				Paper/ Embossed				Paper/ Embossed			
(1) 1 th	(L) Lamenth mm		± 0.09	1.00 ±0.10		1.60 ± 0.15				2.01±	0.20		3.20± 0.20				3.20 ± 0.20					
(L) Length	(in.)	n.) (0.024± 0.004)		(0.040±0.004)		(0.063 ± 0.006)			(0.079 ± 0.008) (0.126 ± 0.00					± 0.00	8)	(0.126± 0.008)			3)			
W) Width	mm		±0.09	0.50 ±0.10			0.81 ±0.15				1.25	±0.20		1.60±0.20				2.50±0.20				
w) width	(in.)	(0.011	±0.004)	(0.020±0.004)		004)	(0.032 ±0.006)			(0.049 ±0.008)				(0.063 ±0.008)				(0.098 ±0.008)				
(t) Terminal	mm	0.15±	0.005	0.25±0.15			0.35±0.15			0.50±0.25				0.50±0.25				0.50±0.25				
(t) Terrilliai	(in.)	(0.006±0.002)		(0.010±0.006)			(0.014±0.006)			(0.020±0.010)				(0.020±0.010)				(0.020±0.010)				
	WVDC	6.3	10	6	10	16	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50
Сар	820																					
(pF)	1000	Α	Α																			
	2200	Α	Α																			
	4700	Α	Α																			
Сар	0.010	Α	Α	Α	Α	Α	Α	Α	Α	Α	Υ	Υ	Υ	Υ	Z	Z	Z	Z				
(μF)	0.022	Α		Α	Α	Α	Α	Α	Α	Α	Υ	Υ	Υ	Υ	Z	Z	Z	Z				\square
	0.047	Α		Α	Α	Α	Α	Α	Α	Α	Υ	Υ	Υ	Υ	Z	Z	Z	Z				
	0.10	Α		Α	Α	Α	Α	Α	Α	Α	С	С	С	С	Z	Z	Z	Z	С	С	С	С
	0.22			Α	Α	Α	Α	Α	Α	Α	С	С	С	С	Z	Z	Z	Z	С	С	С	С
	0.33			Α	Α	Α	Α	Α	Α		С	С	С	С	В	В	В	В	С	С	С	С
	0.47			Α	Α	Α	Α	Α	Α		С	С	С	С	В	В	В	В	С	С	С	С
	1.0			Α	Α		Α	Α	Α		Α	Α	Α	Α	N	N	N	N	Н	Н	Н	Н
	2.2						Α	Α			Α	Α	Α		Α	Α	Α	Α	L	L	L	L
	4.7						Α				Α	Α			Α	Α	Α		L	L	L	Α
	10.0										A				Α	A	K		K	K	Н	L
	22.0										Α				Α	Α			K	L		\square
	47.0																					
0175	WVDC	6.3	10	6	10	16	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50
SIZE		02	01		0402			0603		0805			1206				1210					



Case Size	0201 (KGM 03)	0402 (KGM 05)	0603 (KGM 15)	80	0805 (KGM 21)			120	06 (KGM	31)		1210 (KGM 32)					
Thickness Letter	Α	Α	Α	Υ	С	Α	Z	В	N	Α	K	С	Н	K	Α	L	
Max Thickness(mm)	0.33	0.55	0.90	0.76	0.95	1.45	0.76	0.94	1.27	1.80	2.29	1.27	1.80	2.29	2.70	2.80	
Carrier Tape	PAPER	PAPER	PAPER	EMB	EMB	EMB	EMB	EMB	EMB	EMB	EMB	EMB	EMB	EMB	EMB	EMB	
Packaging Code 7"reel	Н	Н	Т	T	Т	U	Т	Т	U	U	U	U	U	U	U	U	
Packaging Code 13"reel	N	N	М	М	М	L	М	М	L	L	L	L	L	L	L	L	
		PAPER EMB			PAPER EMB				EMB								